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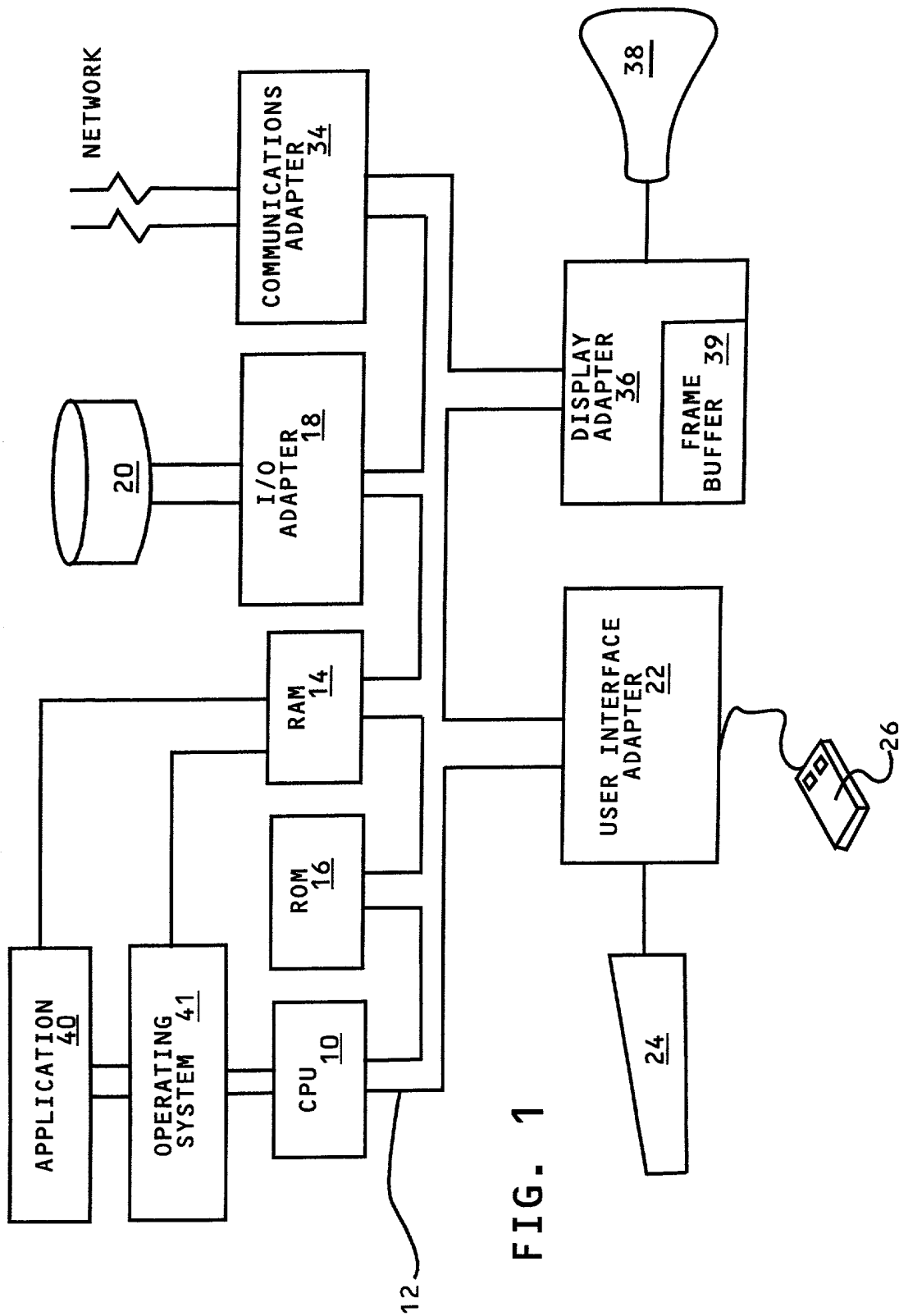


FIG. 1

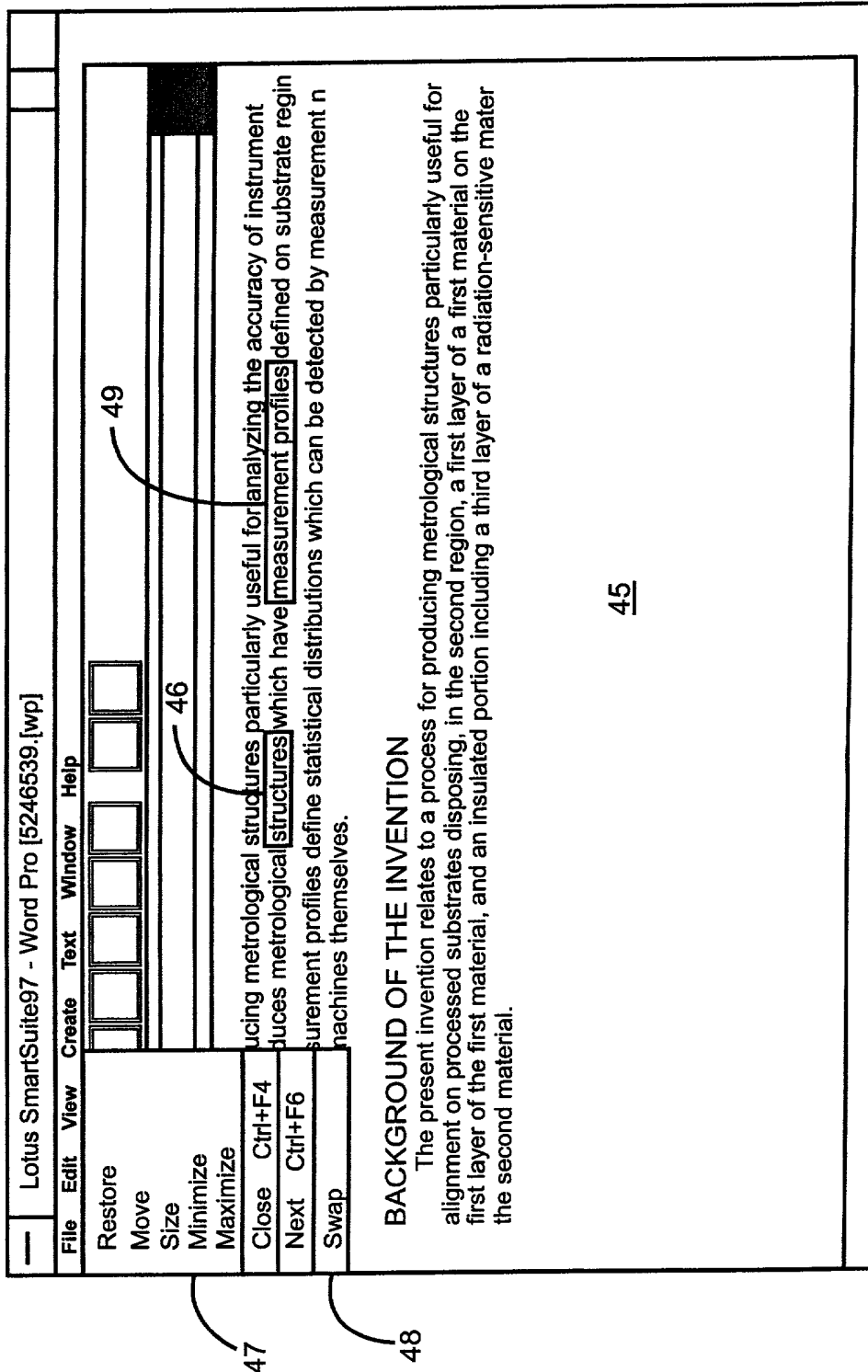


FIG. 2

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<p>Abstract: Process for producing metrological structures particularly useful for analyzing the accuracy of instrument The process produces metrological <u>measurement profiles</u> which have <u>structure</u> defined on substrate regin wafer. The measurement profiles define statistical distributions which can be detected by measurement n accuracy of the machines themselves.</p> <p style="text-align: center;">49</p> <p>BACKGROUND OF THE INVENTION The present invention relates to a process for producing metrological structures particularly useful for alignment on processed substrates disposing, in the second region, a first layer of a first material on the first layer of the first material, and an insulated portion including a third layer of a radiation-sensitive mater the second material.</p> <p style="text-align: center;">46</p>									
45									

FIG. 3

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50 54													
Abstract: Process for producing metrological structures particularly useful for analyzing the accuracy of insubstrates. The process produces measurement profiles which have structures original measurement profiles define statistical distributions which can be detected by measure accuracy of the machines themselves.													
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51 45 55													

FIG. 4

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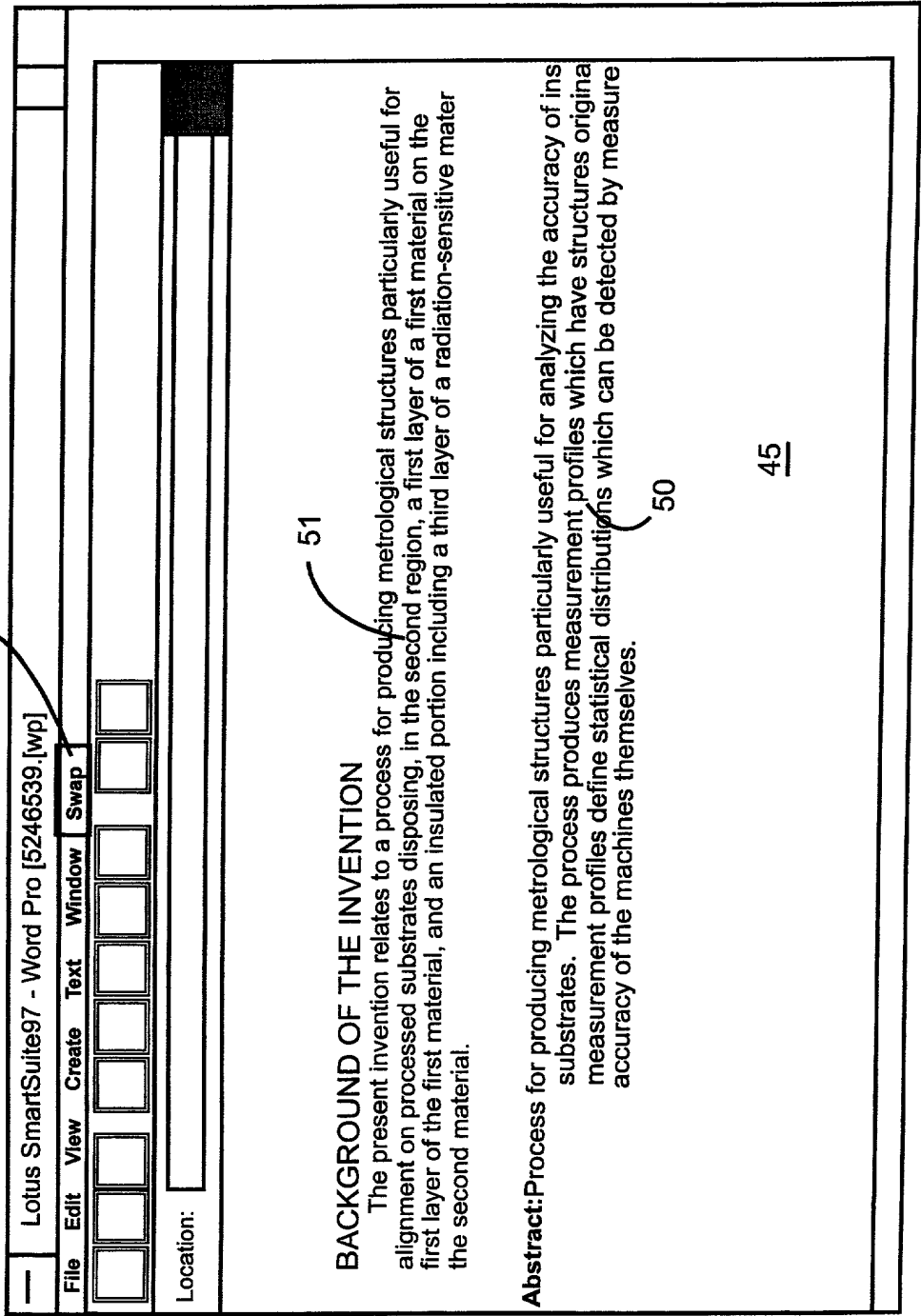


FIG. 5

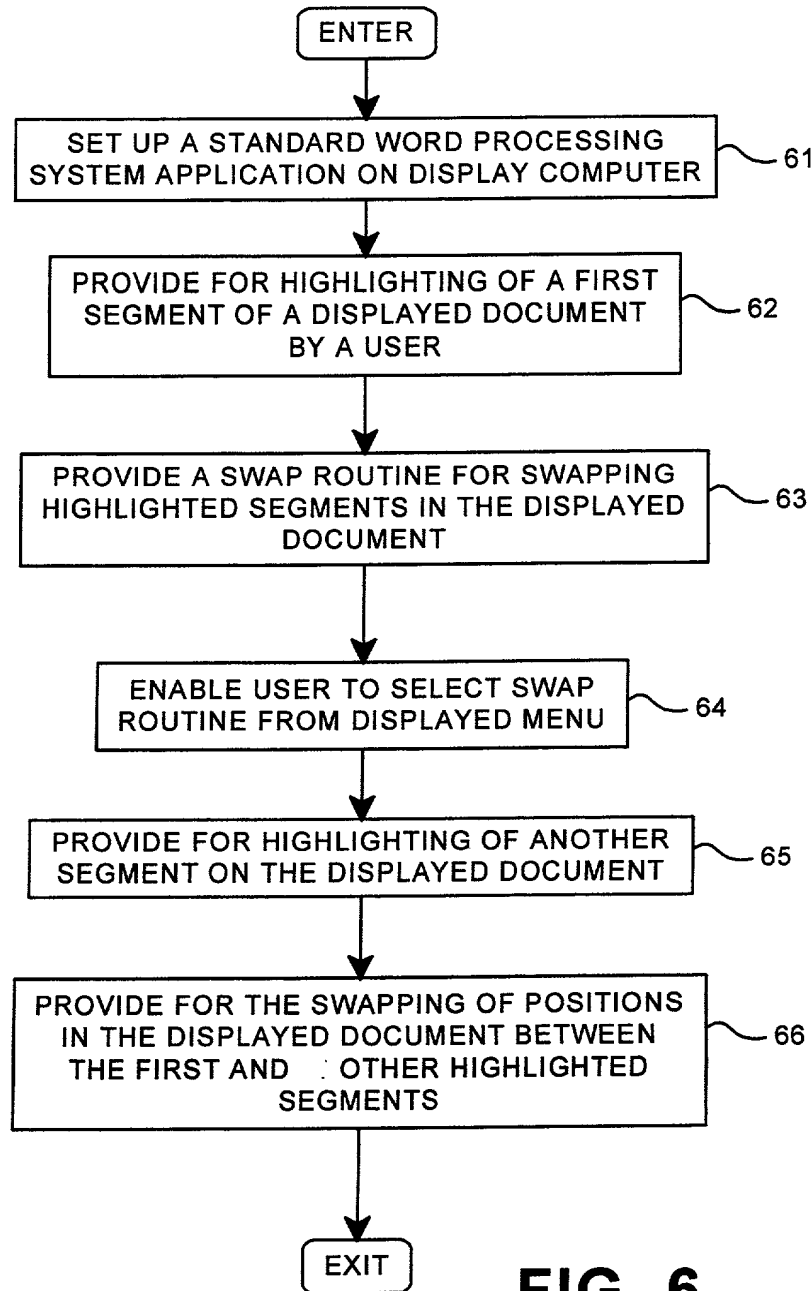


FIG. 6

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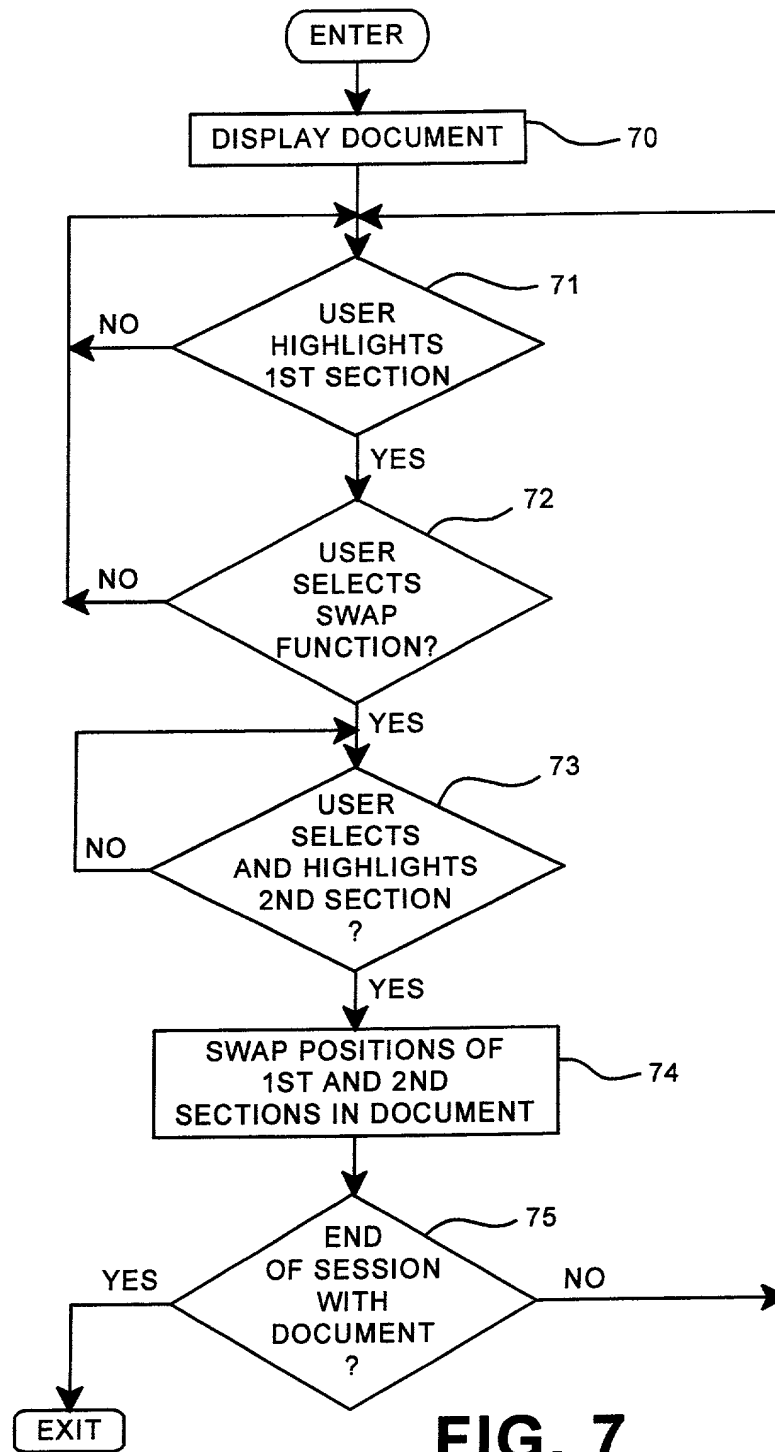


FIG. 7